

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of the claims in the application:

Listing of Claims:

1. (Currently Amended) A computer-implemented method comprising:
measuring electrical characteristics of an interconnection; and
determining a test network having electrical characteristics such that the electrical characteristics of the interconnection are approximated by the electrical characteristics of the test network within a specified tolerance.
2. (Original) The method of claim 1 wherein the test network is a resistive/capacitive network.
3. (Original) The method of claim 2 wherein measuring includes creating a graphical representation of an output of the interconnection.
4. (Original) The method of claim 3 wherein determining includes creating a graphical representation of an output of the resistive/capacitive network that approximates the graphical representation of the output of the interconnection within a specified tolerance.

5. (Original) The method of claim 4 wherein the specified tolerance is 10%.
6. (Original) The method of claim 1 wherein the test network is a resistive network.
7. (Original) The method of claim 1 wherein the test network is a capacitive network.
8. (Original) The method of claim 1 wherein the test network is comprised of a plurality of resistive/capacitive networks.
9. (Original) The method of claim 2 further including:
connecting the resistive/capacitive network between a driver of a first input/output circuit and a receiver of a second input/output circuit.
10. (Original) The method of claim 2 further including:
connecting the resistive/capacitive network between a driver of an input/output circuit and a receiver of the input/output circuit.
11. (Original) The method of claim 10 wherein the resistance and capacitance of the resistive/capacitive network are adjustable.
12. (Original) The method of claim 11 wherein the resistive/capacitive network is implemented on an integrated circuit chip.

13. (Currently Amended) The method of claim 12 wherein the capacitance is distributed RC ~~ladder~~ gate capacitance.

14. (Original) The method of claim 11 wherein the resistive/capacitive network is implemented on a printed circuit board.

15. (Original) An apparatus comprising:

an integrated circuit having at least one input/output ports, the at least one input/output ports having a driver and a receiver; and

a test network electrically coupling the driver and the receiver such that an input/output interface interconnection may be emulated therewith.

16. (Original) The apparatus of claim 15 wherein the test network is a resistive/capacitive network.

17. (Original) The apparatus of claim 15 wherein the test network is a resistive network.

18. (Original) The apparatus of claim 15 wherein the test network is a capacitive network.

19. (Original) The apparatus of claim 16 wherein the resistance and capacitance of the resistive/capacitive network are adjustable.

20. (Original) The apparatus of claim 16 wherein the integrated circuit and the resistive/capacitive network are implemented on a same integrated circuit chip.

21. (Original) The apparatus of claim 16 wherein the resistive/capacitive network is implemented on a printed circuit board.
22. (Original) The apparatus of claim 15 wherein the integrated circuit is part of a microprocessor.
23. (Original) An apparatus comprising:
a test network for an input/output interface having elements selected such that electrical characteristics of the test network approximate electrical characteristics of an input/output interface interconnection within a specified tolerance.
24. (Original) The apparatus of claim 23 wherein the elements are resistive elements and capacitive elements.
25. (Original) The apparatus of claim 24 wherein the resistive elements and the capacitive elements are adjustable such that the test network may be used to approximate the electrical characteristics of a plurality of input/output interface interconnections.
26. (Original) The apparatus of claim 24 wherein the test network is comprised of a plurality of resistive/capacitive networks.
27. (Original) The apparatus of claim 26 wherein the capacitive elements are distributed RC ladder.

28. (Original) The apparatus of claim 27 implemented within an integrated circuit chip.
29. (Original) The apparatus of claim 27 implemented on a printed circuit board.
30. (Original) The apparatus of claim 23 wherein the elements are determined such that a graphical representation of an output of the test network approximates, within a specified tolerance, the graphical representation of an output of a particular input/output interface interconnection.